

PATENT

DOCKET NO.: Intel 2207/1212002

ASSIGNEE: Intel Corporation

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANTS : Jayaraman, Kaikumar, et al.

SERIAL NO. OF
PARENT APPLICATION : 10/028,393


FILING DATE OF
PARENT APPLICATION : December 21, 2001

FOR : ANHYDRIDE POLYMERS FOR USE AS
CURING AGENTS IN EPOXY RESIN-
BASED UNDERFILL MATERIAL

ART UNIT OF
PARENT APPLICATION : 1712

EXAMINER FOR
PARENT APPLICATION : KEEHAN, Christopher M.

M/S: PATENT APPLICATION
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING	
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: M/S: PATENT APPLICATION, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on	
Dated: July 8, 2003	Signature  Edward S. Quon

PRELIMINARY AMENDMENT

Dear Sir:

In response to the Office Action dated January 24, 2002, please cancel claims 1-18 in this Divisional application, leaving claims 19-24, prior to calculating fees.

Applicant elected to prosecute claims 1-18 in the parent application and filed this Divisional application to prosecute the remaining claims, 19-24. This application claims benefit of the December 21, 2001, filing date of the above-mentioned parent application.

Amendment to the Specification begins on page 2 of this paper.